

Process Change Notice #1305101

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PCN Date: 5/10/2013		Effective Date: 5/15/2013			
Title: Si530-31 Datasheet Revision from 1.3 to 1.4					
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PCN Type:					
□ Datasheet	eet		ndry		Packing
☐ Product Revision	Revision		mbly 🗌 Labo		_abeling
☐ Discontinuance ☐ Test		☐ Other		Other	
Last Order Date: N/A					
PCN Details					
Description of Change: Silicon Labs is pleased to announce rev 1.4 datasheet for the Si530-31 devices. Please refer to Appendix A for a list of document changes and access to these datasheets online. The updated data sheet is available at www.silabs.com . If you have questions regarding the					
datasheet, please see your Silicon Labs Sales Representatives. A list of Silicon Labs Sales Representatives is also available at www.silabs.com .					
Reason for Change: This datasheet updates the package diagram and PCB land pattern to conform to JEDEC package drawing requirements. This datasheet change was inadvertently left off the prior datasheet revision.					
Impact on Form, Fit, Function, Quality, Reliability: There is no change to device form, fit, function, quality and reliability.					
Product Identification: Si530, Si531					
Last Date of Unchanged Product: N/A					
Qualification Samples:					
Customer Early Acceptance Sign Off:					
Customers may approve early PCN acceptance by completing the information below:					
Early Acceptance: Date:					
Name:					
Company:					
Email your early Acceptance approval to: katherine.haggar@silabs.com					
Qualification Data:					
N/A					





Appendix A:

Si530-31 datasheet revision 1.3 to 1.4 changes:

- Revised Figure 2 and Table 12 on page 8 to reflect current package outline diagram.
- Revised Figure 4 and Table 14 on page 10 to reflect the recommended PCB land pattern.